

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claims 1-15 (canceled).

Claim 16. (original): A composite electronic component comprising:

a first case member;

a surface acoustic wave device mounted on the first case member and which includes a package, a surface acoustic wave element accommodated within the package, and a ground terminal, the package having a conductor in at least one portion thereof; and

a conductive second case member to be connected to a ground potential and fixed to the first case member, the conductive second case member having an opening in one portion opposing the conductor of the package.

Claim 17. (original): A component according to Claim 16, wherein the first case member is a planar case circuit board and the second case member includes a top plate and an annular side-wall extending downwardly from the periphery of the top plate so as to surround the surface acoustic wave device mounted on the planar first case member.

Claim 18. (original): A component according to Claims 16, wherein the second case member is made of a metal.

Claim 19. (original): A component according to Claim 16, wherein the second case member is made of an insulator and a conductive film disposed on the external surface of the insulator.

Claim 20. (original): A component according to Claim 16, wherein the package includes first and second package members, the surface acoustic wave element being mounted on the first package member, the second package member having the conductor.

Claim 21. (original): A component according to Claim 20, wherein the first package member includes a bottom plate and an annular side-wall extending upwardly from the periphery of the bottom plate so as to have an opening opened upwardly and the second package member is a planar lid which is fixed so as to close the opening of the first package.

Claim 22. (original): A component according to Claim 20, wherein the first package member is a planar package circuit board and the second package member includes a top plate and an annular side-wall extending downwardly from the periphery of the top plate so as to surround the surface acoustic wave element mounted on the planar package circuit board.

Claim 23. (original): A component according to Claim 22, wherein the second package member includes a metallic cap.

Claim 24. (original): A component according to Claim 16, wherein a plurality of the surface acoustic wave devices are mounted on the first case member.

Claim 25. (original): A component according to Claim 16, wherein the surface acoustic wave device includes a plurality of surface acoustic wave elements.

Claim 26. (original): A component according to Claim 25, wherein each of the plurality of surface acoustic wave elements has a ladder-type circuit structure including a series arm resonator and a parallel arm resonator.

Claim 27. (original): A component according to Claim 16, wherein the composite electronic component is a duplexer.

Claim 28. (original): A communication device comprising a composite electronic component according to Claim 16.